Kingbright

L-154A4SURKQBDZGW

T-1 3/4 (5mm) Full Color LED Lamp

DESCRIPTIONS

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- The Blue source color devices are made with InGaN Light Emitting Diode
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode
- Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- All devices, equipments and machineries must be electrically grounded

FEATURES

- Uniform light output
- Low power consumption
- Long life-solid state reliability
- RoHS compliant

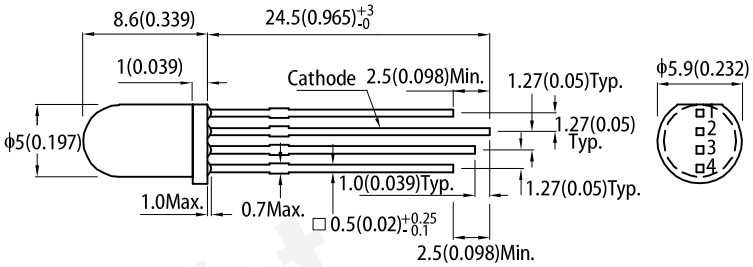
APPLICATIONS

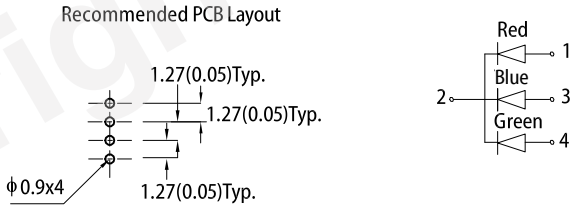
- Status indicator
- Illuminator
- Signage applications
- Decorative and entertainment lighting
- Commercial and residential architectural lighting

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices

PACKAGE DIMENSIONS





Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA [2]		Viewing Angle [1]
			Min.	Typ.	2θ1/2
L-154A4SURKQBDZGW	Hyper Red (AlGaInP)	White Diffused	300	700	60°
			*100	*200	
	Blue (InGaN)		120	300	
			*120	*300	
	Green (InGaN)		600	1300	
			*600	*1300	

Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous flux: +/-15%.
** Luminous intensity value is traceable to CIE127-2007 standards.*

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
			Typ.	Max.	
Wavelength at Peak Emission I_F = 20mA	λ_{peak}	Hyper Red Blue Green	645 460 515	-	nm
Dominant Wavelength I_F = 20mA	λ_{dom} [1]	Hyper Red Blue Green	630 465 525	-	nm
Spectral Bandwidth at 50% Φ REL MAX I_F = 20mA	Δλ	Hyper Red Blue Green	28 25 30	-	nm
Capacitance	C	Hyper Red Blue Green	35 100 45	-	pF
Forward Voltage I_F = 20mA	V_F [2]	Hyper Red Blue Green	1.95 3.3 3.3	2.5 4.0 4.1	V
Reverse Current (V_R = 5V)	I_R	Hyper Red Blue Green	-	10 50 50	μA
Temperature Coefficient of λ_{peak} I_F = 20mA, -10°C ≤ T ≤ 85°C	$TC_{\lambda peak}$	Hyper Red Blue Green	0.14 0.04 0.05	-	nm/°C
Temperature Coefficient of λ_{dom} I_F = 20mA, -10°C ≤ T ≤ 85°C	$TC_{\lambda dom}$	Hyper Red Blue Green	0.05 0.03 0.03	-	nm/°C
Temperature Coefficient of V_F I_F = 20mA, -10°C ≤ T ≤ 85°C	TC_V	Hyper Red Blue Green	-1.9 -3.0 -3.0	-	mV/°C

Notes:
1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ±1nm.)
2. Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

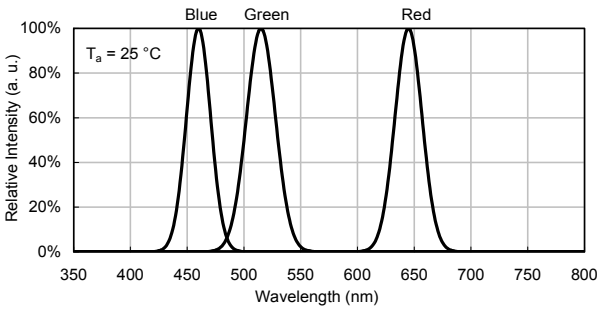
ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter	Symbol	Value			Unit
		Hyper Red	Blue	Green	
Power Dissipation	P_D	75	120	102.5	mW
Reverse Voltage	V_R	5	5	5	V
Junction Temperature	T_j	115	115	115	°C
Operating Temperature	T_{op}	-40 to +85			°C
Storage Temperature	T_{stg}	-40 to +85			°C
DC Forward Current	I_F	30	30	25	mA
Peak Forward Current	I_{FM} [1]	185	150	150	mA
Electrostatic Discharge Threshold (HBM)	-	3000	250	450	V
Thermal Resistance (Junction / Ambient)	$R_{th\ JA}$ [2]	300	270	380	°C/W
Thermal Resistance (Junction / Solder point)	$R_{th\ JS}$ [2]	190	170	270	°C/W
Lead Solder Temperature [3]		260°C For 3 Seconds			
Lead Solder Temperature [4]		260°C For 5 Seconds			

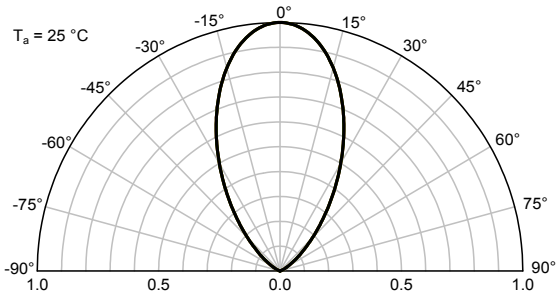
Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. $R_{th\ JA}$,$R_{th\ JS}$ Results from mounting on PC board FR4 (pad size ≥ 16 mm^2 per pad).
3. 2mm below package base.
4. 5mm below package base.
5. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA

RELATIVE INTENSITY vs. WAVELENGTH

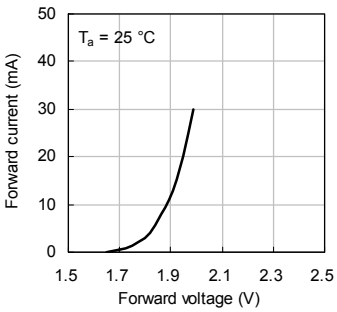


SPATIAL DISTRIBUTION

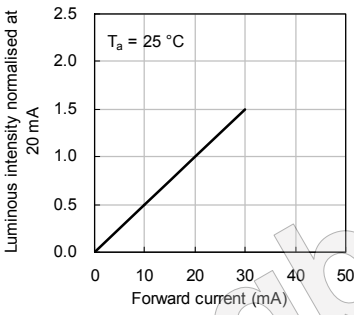


HYPER RED

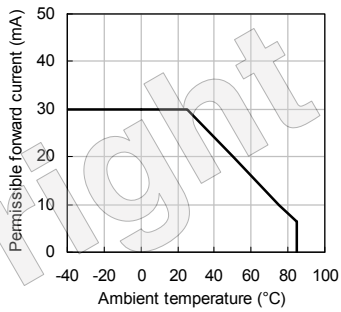
Forward Current vs. Forward Voltage



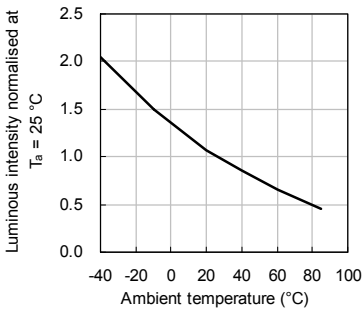
Luminous Intensity vs. Forward Current



Forward Current Derating Curve

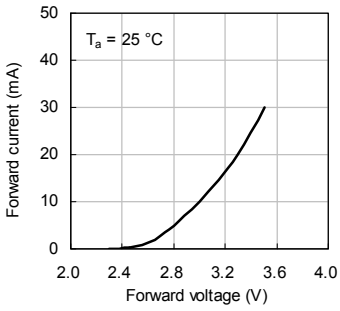


Luminous Intensity vs. Ambient Temperature

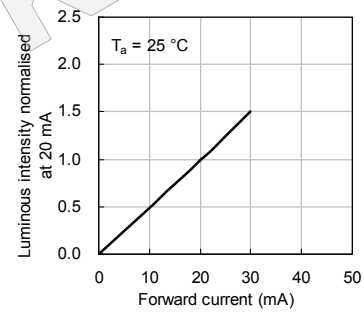


BLUE

Forward Current vs. Forward Voltage



Luminous Intensity vs. Forward Current



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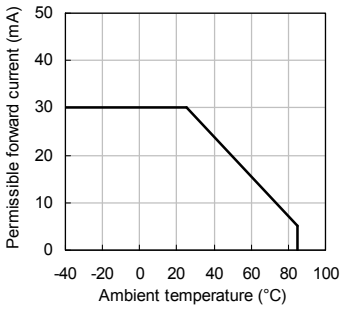
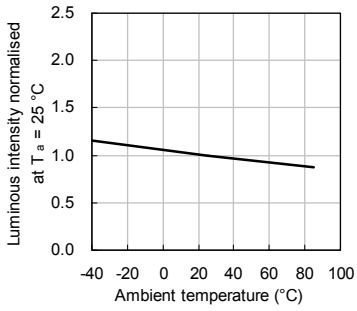
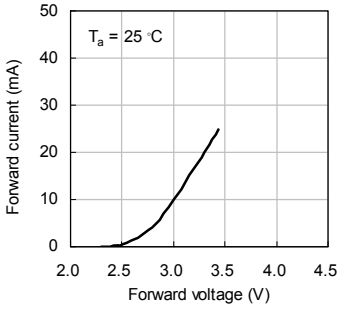


Luminous Intensity vs. Ambient Temperature

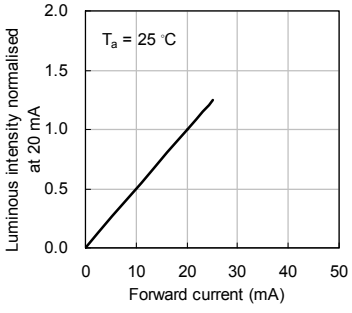


GREEN

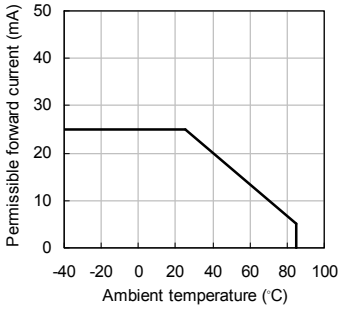
Forward Current vs. Forward Voltage



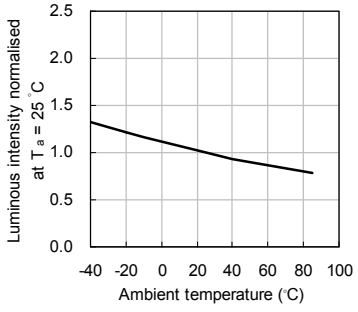
Luminous Intensity vs. Forward Current



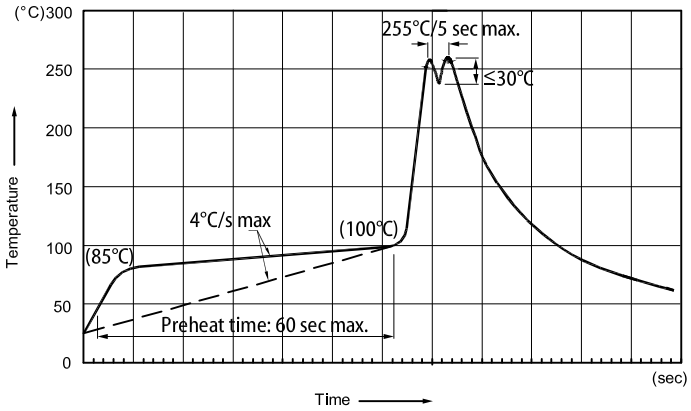
Forward Current Derating Curve



Luminous Intensity vs. Ambient Temperature



RECOMMENDED WAVE SOLDERING PROFILE



Notes:
1. *Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C*
2. *Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).*
3. *Do not apply stress to the epoxy resin while the temperature is above 85°C.*
4. *Fixtures should not incur stress on the component when mounting and during soldering process.*
5. *SAC 305 solder alloy is recommended.*
6. *No more than one wave soldering pass.*

PRECAUTIONS

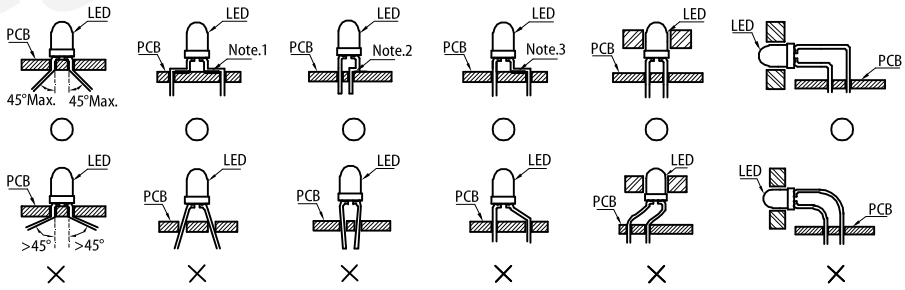
Storage conditions

1. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
2. LEDs should be stored with temperature ≤ 30°C and relative humidity < 60%.
3. Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.

LED Mounting Method

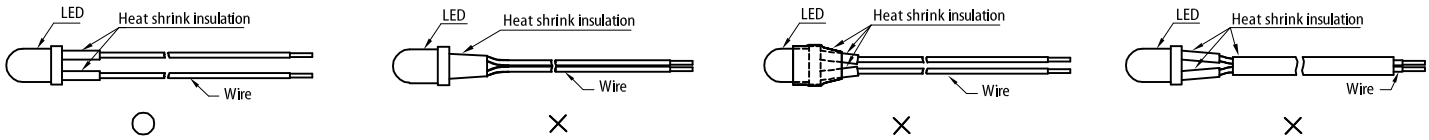
1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

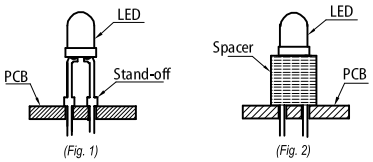
Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.



" ○ " *Correct mounting method* " x " *Incorrect mounting method*

2. When soldering wires to the LED, each wire joint should be separately insulated with heat-shrink tube to prevent short-circuit contact. Do not bundle both wires in one heat shrink tube to avoid pinching the LED leads. Pinching stress on the LED leads may damage the internal structures and cause failure.

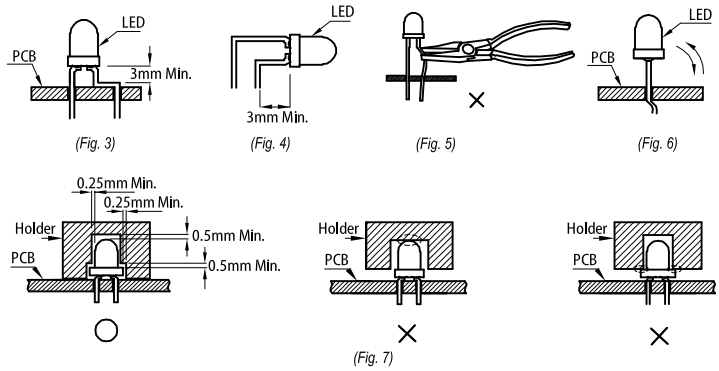




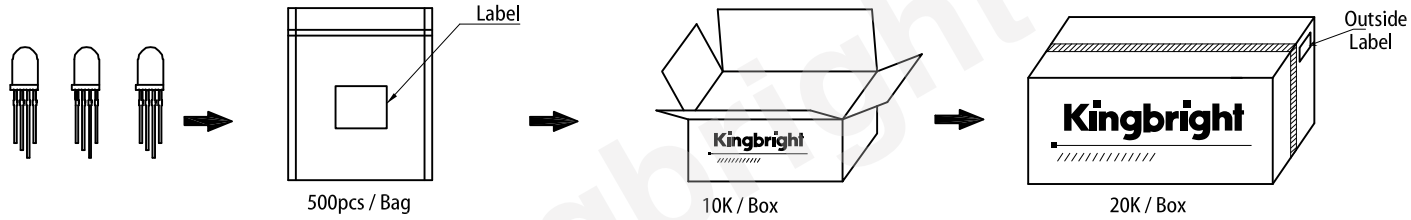
3. Use stand-offs *(Fig.1)* or spacers *(Fig.2)* to securely position the LED above the PCB.
4. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend *(Fig. 3 ,Fig. 4)*.
5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. *(Fig. 5)*

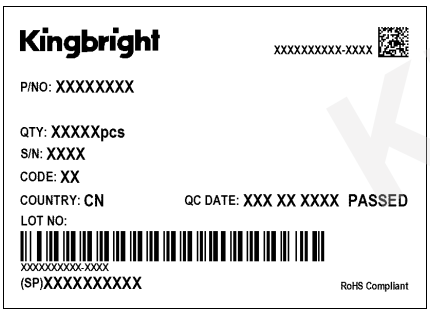
Lead Forming Procedures

1. Do not bend the leads more than twice. *(Fig. 6)*
2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering. *(Fig. 7)*
3. The tip of the soldering iron should never touch the lens epoxy.
4. Through-hole LEDs are incompatible with reflow soldering.
5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.



PACKING & LABEL SPECIFICATIONS





PRECAUTIONARY NOTES

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
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